HD74LS107A

Dual J-K Negative-edge-triggered Flip-Flops (with Clear)

REJ03D0425–0300
Rev.3.00
Jul.13.2005

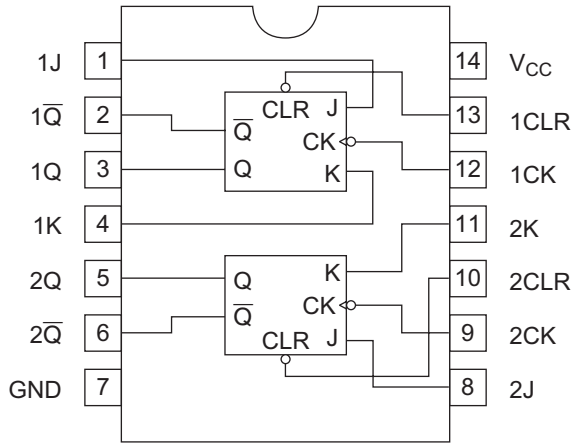
Features

- Ordering Information

Part Name	Package Type	Package Code (Previous Code)	Package Abbreviation	Taping Abbreviation (Quantity)
HD74LS107AP	DILP-14 pin	PRDP0014AB-B (DP-14AV)	P	—
HD74LS107AFPEL	SOP-14 pin (JEITA)	PRSP0014DF-B (FP-14DAV)	FP	EL (2,000 pcs/reel)

Note: Please consult the sales office for the above package availability.

Pin Arrangement



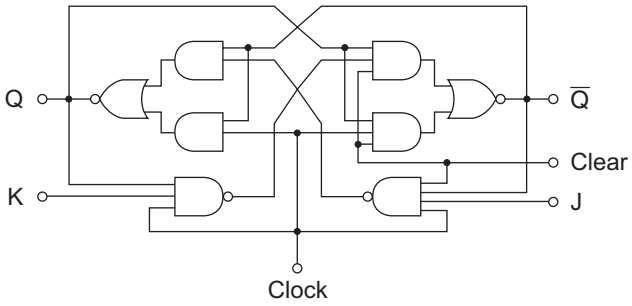
(Top view)

Function Table

Inputs				Outputs	
Clear	Clock	J	K	Q	$\overline{Q}$
L	X	X	X	L	H
H	↓	L	L	Q_O	$\overline{Q}_O$
H	↓	H	L	H	L
H	↓	L	H	L	H
H	↓	H	H	Toggle	
H	H	X	X	Q_O	$\overline{Q}_O$

Notes: H; high level, L; low level, X; irrelevant
↓; transition from high to low level
Q; level of Q before the indicated steady-state input conditions were established.
$\overline{Q}$; complement of Q_O or level of $\overline{Q}$ before the indicated steady-state input conditions were established.
Toggle; each output changes to the complement of its previous level on each active transition indicated by ↓.

Block Diagram (1/2)



Absolute Maximum Ratings

Item	Symbol	Ratings	Unit
Supply voltage	V_{CC}	7	V
Input voltage	V_{IN}	7	V
Power dissipation	P_T	400	mW
Storage temperature	Tstg	–65 to +150	°C

Note: Voltage value, unless otherwise noted, are with respect to network ground terminal.

Recommended Operating Conditions

Item		Symbol	Min	Typ	Max	Unit
Supply voltage		V_{CC}	4.75	5.00	5.25	V
Output current		I_{OH}	—	—	–400	µA
		I_{OL}	—	—	8	mA
Operating temperature		Topr	–20	25	75	°C
Clock frequency		f_{clock}	0	—	30	MHz
Pulse width	Clock High	t_w	20	—	—	ns
	Clear Low		25	—	—	ns
Setup time	“H” Data	t_{su}	20↓	—	—	ns
	“L” Data		20↓	—	—	ns
Hold time		t_h	0↓	—	—	ns

Electrical Characteristics

(Ta = –20 to +75 °C)

Item		Symbol	min.	typ.*	max.	Unit	Condition
Input voltage		V_{IH}	2.0	—	—	V	
		V_{IL}	—	—	0.8	V	
Output voltage		V_{OH}	2.7	—	—	V	V_{CC} = 4.75 V, V_{IH} = 2 V, V_{IL} = 0.8 V, I_{OH} = –400 µA
		V_{OL}	—	—	0.5	V	I_{OL} = 8 mA, V_{CC} = 4.75 V, V_{IH} = 2 V, V_{IL} = 0.8 V
			—	—	0.4		I_{OL} = 4 mA
Input current	J, K	I_{IH}	—	—	20	µA	V_{CC} = 5.25 V, V_I = 2.7 V
	Clear		—	—	60		
	Clock		—	—	80		
	J, K	I_{IL}	—	—	–0.4	mA	V_{CC} = 5.25 V, V_I = 0.4 V
	Clear		—	—	–0.8		
	Clock		—	—	–0.8		
	J, K	I_I	—	—	0.1	mA	V_{CC} = 5.25 V, V_I = 7 V
	Clear		—	—	0.3		
	Clock		—	—	0.4		
Short-circuit output current		I_{OS}	–20	—	–100	mA	V_{CC} = 5.25 V
Supply current**		I_{CC}	—	4	6	mA	V_{CC} = 5.25 V
Input clamp voltage		V_{Ik}	—	—	–1.5	V	V_{CC} = 4.75 V, I_{IN} = –18 mA

Notes: * V_{CC} = 5 V, Ta = 25°C

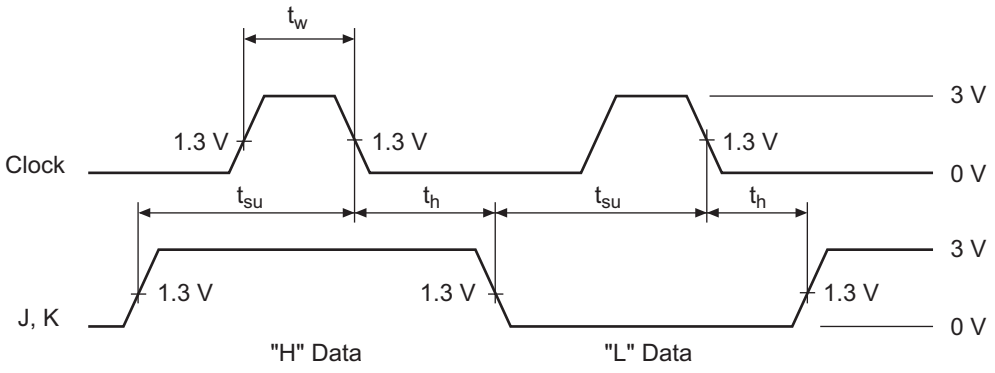
** With all outputs open, I_{CC} is measured with the Q and $\overline{Q}$ outputs high in turn. At the tires of measurement, the clock input is grounded.

Switching Characteristics

(V_{CC} = 5 V, Ta = 25°C)

Item	Symbol	Inputs	Outputs	min.	typ.	max.	Unit	Condition
Maximum clock frequency	f_{max}			30	45	—	MHz	C_L = 15 pF, R_L = 2 kΩ
Propagation delay time	t_{PLH}	Clear Clock	Q, $\overline{Q}$	—	15	20	ns	
	t_{PHL}			—	15	20	ns	

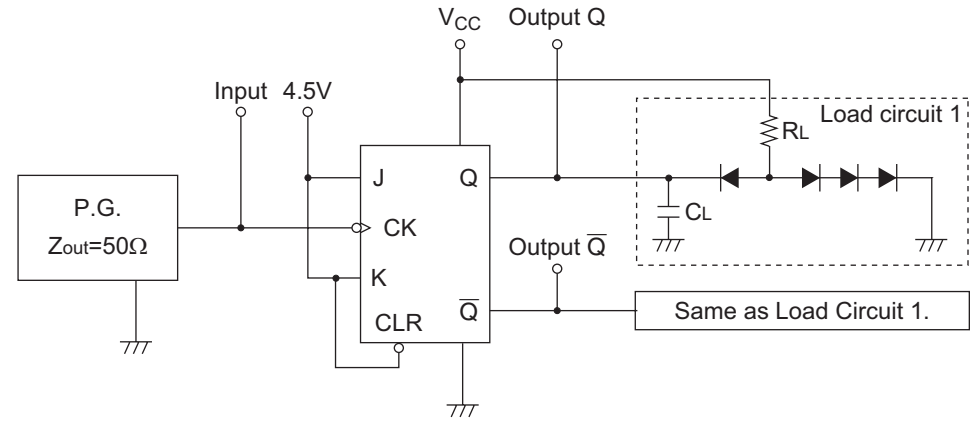
Timing Definition



Testing Method

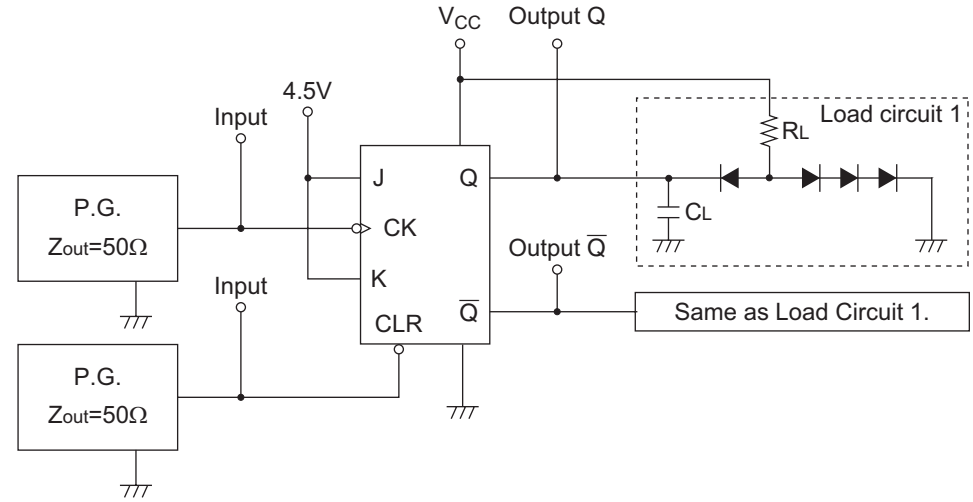
Test Circuit

1. f_{max}, t_{PLH}, t_{PHL}, (Clock→Q, $\overline{Q}$)



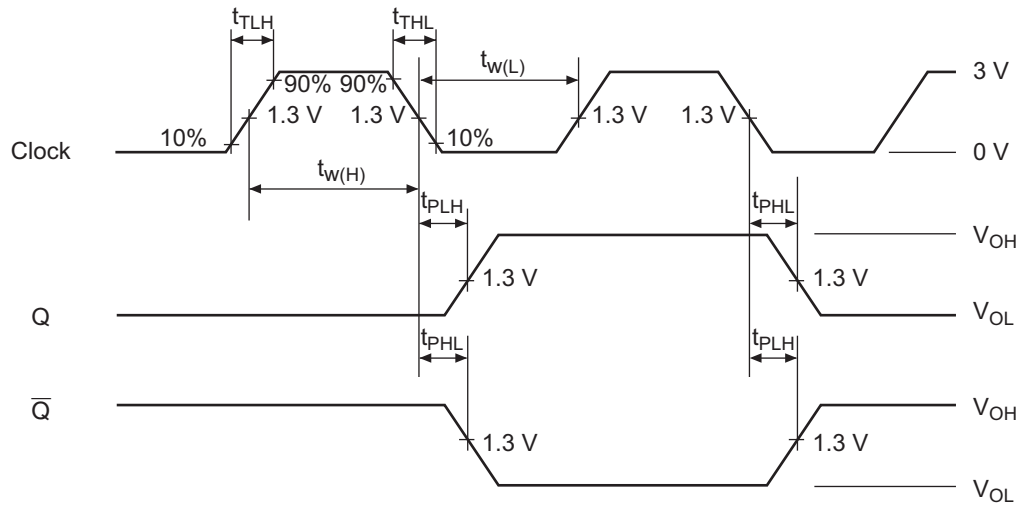
Notes:
1. Test is put into the each flip-flop.
2. C_L includes probe and jig capacitance.
3. All diodes are 1S2074(H).

2. t_{PHL} (Clear→Q), t_{PLH} (Clear→$\overline{Q}$)



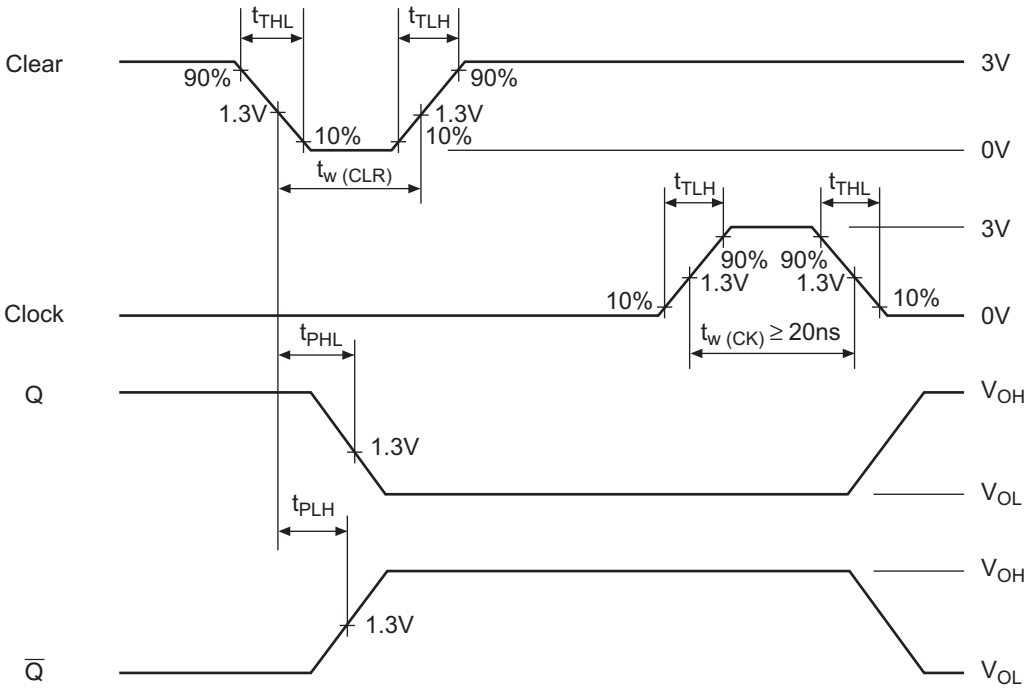
Notes:
1. Test is put into the each flip-flop.
2. C_L includes probe and jig capacitance.
3. All diodes are 1S2074(H).

Waveforms 1



Note: Clock input pulse: $t_{TLH} \leq 15$ ns, $t_{THL} \leq 6$ ns, PRR = 1 MHz, duty cycle = 50% and: for f_{max}, t_{THL} $t_{THL} \leq 2.5$ ns.

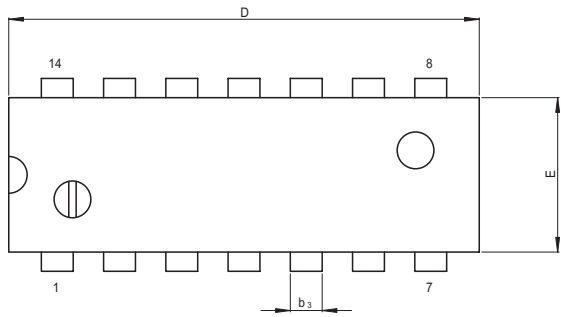
Waveforms 2

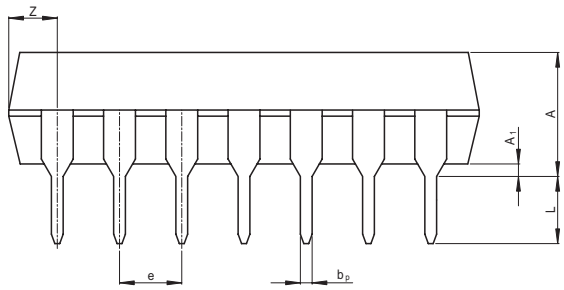


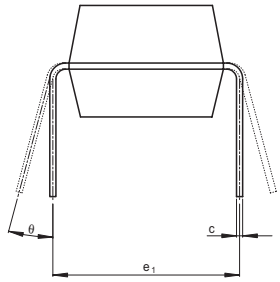
Note: Clear and clock input pulse: $t_{TLH} \leq 15$ ns, $t_{THL} \leq 6$ ns, PRR = 1 MHz.

Package Dimensions

JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
P-DIP14-6.3x19.2-2.54	PRDP0014AB-B	DP-14AV	0.97g



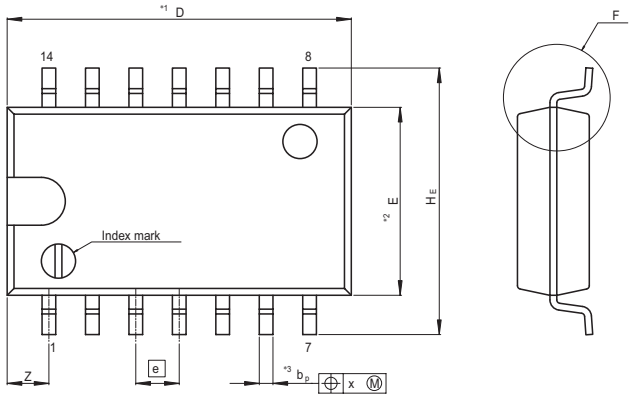


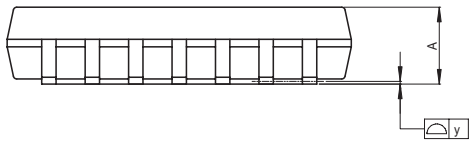


(Ni/Pd/Au plating)

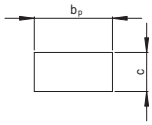
Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
e_1	——	7.62	——
D	——	19.2	20.32
E	——	6.3	7.4
A	——	——	5.06
A_1	0.51	——	——
b_p	0.40	0.48	0.56
b_3	——	1.30	——
c	0.19	0.25	0.31
θ	0°	——	15°
e	2.29	2.54	2.79
Z	——	——	2.39
L	2.54	——	——

JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
P-SOP14-5.5x10.06-1.27	PRSP0014DF-B	FP-14DAV	0.23g

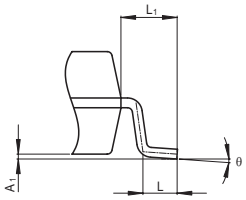




NOTE)
1. DIMENSIONS"*1 (Nom)"AND"*2" DO NOT INCLUDE MOLD FLASH.
2. DIMENSION"*3"DOES NOT INCLUDE TRIM OFFSET.



Terminal cross section
(Ni/Pd/Au plating)



Detail F

Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	——	10.06	10.5
E	——	5.50	——
A_2	——	——	——
A_1	0.00	0.10	0.20
A	——	——	2.20
b_p	0.34	0.40	0.46
b_1	——	——	——
c	0.15	0.20	0.25
c_1	——	——	——
θ	0°	——	8°
H_E	7.50	7.80	8.00
e	——	1.27	——
x	——	——	0.12
y	——	——	0.15
Z	——	——	1.42
L	0.50	0.70	0.90
L_1	——	1.15	——

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